# **Dual D-Type Positive Edge-Triggered Flip-Flop**

The MC74AC74/74ACT74 is a dual D–type flip–flop with Asynchronous Clear and Set inputs and complementary  $(Q,\overline{Q})$  outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. Clock triggering occurs at a voltage level of the clock pulse and is not directly related to the transition time of the positive-going pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

Asynchronous Inputs: I OW input to  $\overline{S}_{D}$  (Set

LOW input to  $\overline{S}_D$  (Set) sets Q to HIGH level

LOW input to  $\overline{C}_D$  (Clear) sets Q to LOW level

Clear and Set are independent of clock

Simultaneous LOW on  $\overline{C}_D$  and  $\overline{S}_D$  makes both Q and  $\overline{Q}$  HIGH

#### **Features**

- Outputs Source/Sink 24 mA
- 'ACT74 Has TTL Compatible Inputs
- These are Pb-Free Devices

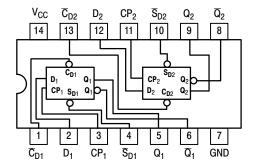


Figure 1. Pinout: 14-Lead Packages Conductors (Top View)

#### **PIN ASSIGNMENT**

PIN	FUNCTION
D <sub>1</sub> , D <sub>2</sub>	Data Inputs
CP <sub>1</sub> , CP <sub>2</sub>	Clock Pulse Inputs
$\overline{C}_{D1}, \overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1}, \overline{S}_{D2}$	Direct Set Inputs
$\overline{Q}_1, \overline{Q}_1, Q_2, \overline{Q}_2$	Outputs



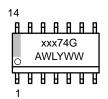
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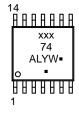


SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G



xxx = AC or ACT

A = Assembly Location

WL or L = Wafer Lot Y = Year WW or W = Work Week

G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

TRUTH TABLE (Each Half)

	Inp	Out	outs		
<u></u> S <sub>D</sub>	$\overline{C}_{D}$	СР	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	Χ	Χ	L	Н
L	L	Χ	Χ	Н	Н
Н	Н		Н	Н	L
Н	Н		L	L	Н
Н	Н	L	Х	$Q_0$	$\overline{Q}_0$

NOTE: H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial;

 $\square$  = LOW-to-HIGH Clock Transition  $Q_0(\overline{Q}_0)$  = Previous  $Q(\overline{Q})$  before LOW-to-HIGH

Transition of Clock

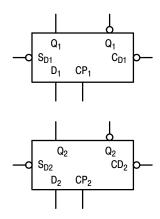
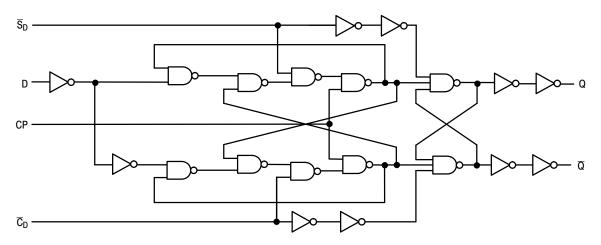


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol	Paramet	ter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5  to  +7.0	V
VI	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
Vo	DC Output Voltage	(Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current		±20	mA
lok	DC Output Diode Current		±50	mA
Io	DC Output Sink/Source Current		±50	mA
Icc	DC Supply Current per Output Pin		±50	mA
I <sub>GND</sub>	DC Ground Current per Output Pin		±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead temperature, 1 mm from Case fo	r 10 Seconds	260	°C
TJ	Junction temperature under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance (Note 2)	SOIC TSSOP	125 170	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	SOIC TSSOP	125 170	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> a	and Below GND at 85°C (Note 6)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I<sub>O</sub> absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD51–7.
   Tested to EIA/JESD22–A114–A.
- 4. Tested to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Тур	Max	Unit
.,	0 1 1 1 1	'AC	2.0	5.0	6.0	.,
V <sub>CC</sub>	Supply Voltage	'ACT	4.5	5.0	5.5	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)	-	0	_	V <sub>CC</sub>	V
			_	150	_	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note )  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	_	40	_	ns/V
AC Devices except Scrimit inputs	The Devices except commit inputs	V <sub>CC</sub> @ 5.5 V	_	25	_	
	Input Rise and Fall Time (Note )	V <sub>CC</sub> @ 4.5 V	_	10	_	//
t <sub>r</sub> , t <sub>f</sub>	'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 5.5 V	_	8.0	_	ns/V
TJ	Junction Temperature (PDIP)		_	_	140	°C
T <sub>A</sub>	Operating Ambient Temperature Range			25	85	°C
I <sub>OH</sub>	Output Current – High		_	_	-24	mA
I <sub>OL</sub>	Output Current – Low		_	_	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

- V<sub>in</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
   V<sub>in</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

## **DC CHARACTERISTICS**

			74	AC	74AC		
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> =	+25°C	T <sub>A</sub> = -40°C to +85°C	Unit	Conditions
			Тур	Guar	Guaranteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I <sub>OUT</sub> = -50 μA
		3.0 4.5 5.5		2.56 3.86 4.86	2.46 3.76 4.76	V	$^*$ V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> $-12$ mA $_{OH}$ $-24$ mA $_{-24}$ mA
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$^*$ V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 12 mA 1 <sub>OL</sub> 24 mA 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
I <sub>OLD</sub>	†Minimum Dynamic	5.5	_	_	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	-	_	-75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	4.0	40	μΑ	$V_{IN} = V_{CC}$ or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I $_{\rm IN}$  and I $_{\rm CC}$  @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V $_{\rm CC}$ .

## **AC CHARACTERISTICS**

				74AC		74AC			
Symbol	Parameter $ \begin{array}{c c} V_{CC}^* & T_A = +25^{\circ}C \\ (V) & C_L = 50 \text{ pF} \end{array} $				Unit	Fig. No.			
			Min	Тур	Max	Min	Max		
f <sub>max</sub>	Maximum Clock Frequency	3.3 5.0	100 140	125 160	_ _	95 125	- -	MHz	3–3
t <sub>PLH</sub>	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to $\overline{Q}_{n}$	3.3 5.0	5.0 3.5	8.0 6.0	12.5 9.0	4.0 3.0	13.0 10.0	ns	3–6
t <sub>PHL</sub>	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to $\overline{Q}_{n}$	3.3 5.0	4.0 3.0	10.5 8.0	12.0 9.5	3.5 2.5	13.5 10.5	ns	3–6
t <sub>PLH</sub>	Propagation Delay $C_{Pn}$ to $Q_n$ or $\overline{Q}_n$	3.3 5.0	4.5 3.5	8.0 6.0	13.5 10.0	4.0 3.0	16.0 10.5	ns	3–6
t <sub>PHL</sub>	Propagation Delay $C_{Pn}$ to $Q_n$ or $\overline{Q}_n$	3.3 5.0	3.5 2.5	8.0 6.0	14.0 10.0	3.5 2.5	14.5 10.5	ns	3–6

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

## **AC OPERATING REQUIREMENTS**

				74AC	74AC		
Symbol	Parameter	V <sub>CC</sub> * (V)					Fig. No.
					d Minimum		
t <sub>s</sub>	Set-up Time, HIGH or LOW D <sub>n</sub> to CP <sub>n</sub>	3.3 5.0	1.5 1.0	4.0 3.0	4.5 3.0	ns	3–9
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP <sub>n</sub>	3.3 5.0	-2.0 -1.5	0.5 0.5	0.5 0.5	ns	3–9
t <sub>w</sub>	C <sub>Pn</sub> or C  Dn or S  Dn  Pulse Width	3.3 5.0	3.0 2.5	5.5 4.5	7.0 5.0	ns	3–6
t <sub>rec</sub>	Recovery Time C <sub>Dn</sub> or S <sub>Dn</sub> to CP	3.3 5.0	-2.5 -2.0	0 0	0 0	ns	3–9

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

## **DC CHARACTERISTICS**

			74 <i>A</i>	CT	74ACT		
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = -	+25°C	T <sub>A</sub> = -40°C to +85°C	Unit	Conditions
			Typ Guara		anteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I <sub>OUT</sub> = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$^*V_{IN} = V_{IL} \text{ or } V_{IH}$ $-24 \text{ mA}$ $I_{OH}$ $-24 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ $24 \text{ mA}$ $I_{OL}$ $24 \text{ mA}$
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	_	1.5	mA	$V_{I} = V_{CC} - 2.1 \text{ V}$
I <sub>OLD</sub>	†Minimum Dynamic	5.5	-	_	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	-	-	<b>-75</b>	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	_	4.0	40	μΑ	$V_{IN} = V_{CC}$ or GND

 $<sup>^{\</sup>star}\text{All}$  outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

## **AC CHARACTERISTICS**

				74ACT		74ACT			
Symbol	Parameter	V <sub>CC</sub> * (V)			T <sub>A</sub> = - to +8 C <sub>L</sub> = 9	35°C	Unit	Fig. No.	
			Min	Тур	Max	Min	Max		
f <sub>max</sub>	Maximum Clock Frequency	5.0	145	210	-	125	-	MHz	3–3
t <sub>PLH</sub>	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to $\overline{Q}_{n}$	5.0	3.0	5.5	9.5	2.5	10.5	ns	3–6
t <sub>PHL</sub>	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to $\overline{Q}_{n}$	5.0	3.0	6.0	10.0	3.0	11.5	ns	3–6
t <sub>PLH</sub>	Propagation Delay $C_{Pn}$ to $Q_n$ or $\overline{Q}_n$	5.0	4.0	7.5	11.0	4.0	13.0	ns	3–6
t <sub>PHL</sub>	Propagation Delay $C_{Pn}$ to $Q_n$ or $\overline{Q}_n$	5.0	3.5	6.0	10.0	3.0	11.5	ns	3–6

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

## **AC OPERATING REQUIREMENTS**

				74ACT	74ACT				
Symbol	Parameter	V <sub>CC</sub> * (V)	T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF						Fig. No.
			Тур	Guaranteed	d Minimum				
t <sub>s</sub>	Set-up Time, HIGH or LOW D <sub>n</sub> to CP <sub>n</sub>	5.0	1.0	3.0	3.5	ns	3–9		
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP <sub>n</sub>	5.0	-0.5	1.0	1.0	ns	3–9		
t <sub>w</sub>	$C_{Pn}$ or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ Pulse Width	5.0	3.0	5.0	6.0	ns	3–6		
t <sub>rec</sub>	Recovery Time $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	5.0	-2.5	0	0	ns	3–9		

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

## **CAPACITANCE**

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	35	pF	V <sub>CC</sub> = 5.0 V

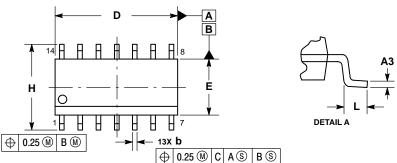
## **ORDERING INFORMATION**

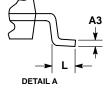
Device	Package	Shipping <sup>†</sup>
MC74AC74DG	SOIC-14 (Pb-Free)	55 Units/Rail
MC74AC74DR2G	SOIC-14 (Pb-Free)	2500/Tape & Reel
MC74AC74DTR2G	TSSOP-14 (Pb-Free)	2500/Tape & Reel
MC74ACT74DG	SOIC-14 (Pb-Free)	55 Units/Rail
MC74ACT74DR2G	SOIC-14 (Pb-Free)	2500/Tape & Reel
MC74ACT74DTR2G	TSSOP-14 (Pb-Free)	2500/Tape & Reel

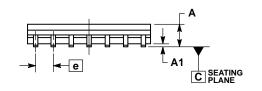
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

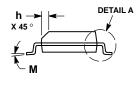
## **PACKAGE DIMENSIONS**

## SOIC-14 NB CASE 751A-03 ISSUE K









#### NOTES:

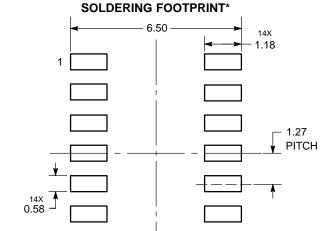
- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAYMM IM MATERIAL CONDITION
- MAXIMUM MATERIAL CONDITION.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

  5. MAXIMUM MOLD PROTRUSION 0.15 PER

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
А3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27 BSC		0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
М	0 °	7°	0 °	7°

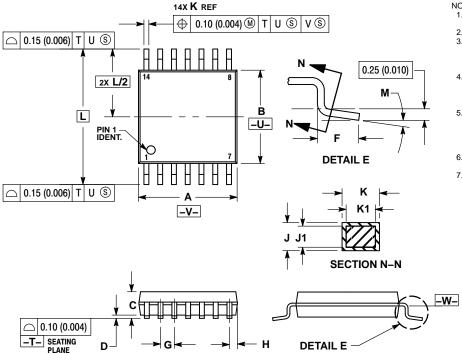


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **PACKAGE DIMENSIONS**

## TSSOP-14 CASE 948G **ISSUE B**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

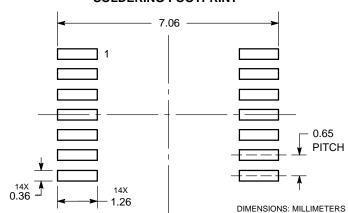
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.06) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. SHALL NOT EXCEED 0.25
- OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- (0.010) PER SIDE.
  DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION, ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN
  EXCESS OF THE K DIMENSION AT MAXIMUM
  MATERIAL CONDITION.
  TERMINAL NUMBERS ARE SHOWN FOR
- TERMINAL NUMBERS ARE SHOWN FOR
- TERMINAL NOMBERS ARE SHOWN FOR REFERENCE ONLY.

   DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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